RELIABILITY REPORT

FOR

MAX5580AEUP+

PLASTIC ENCAPSULATED DEVICES

February 5, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX5580AEUP+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX5580-MAX5585 quad, 12-/10-/8-bit, voltage-output, digital-to-analog converters (DACs) offer buffered outputs and a 3µs maximum settling time at the 12-bit level. The DACs operate from a +2.7V to +5.25V analog supply and a separate +1.8V to +5.25V digital supply. The 20MHz, 3-wire, serial interface is compatible with SPI(tm), QSPI(tm), MICROWIRE(tm), and digital signal processor (DSP) protocol applications. Multiple devices can share a common serial interface in direct-access or daisy-chained configuration. The MAX5580-MAX5585 provide two multifunctional, user-programmable, digital I/O ports. The externally selectable power-up states of the DAC outputs are either zero scale, midscale, or full scale. Software-selectable FAST and SLOW settling modes decrease settling time in FAST mode, or reduce supply current in SLOW mode. The MAX5580/MAX5581 are 12-bit DACs, the MAX5582/MAX5583 are 10-bit DACs, and the MAX5584/MAX5585 are 8-bit DACs. The MAX5580/MAX5582/MAX5584 provide unity-gain-configured output buffers, while the MAX5581/MAX5583/MAX5585 provide force-sense-configured output buffers. The MAX5580-MAX5585 operate over the extended -40°C to +85°C temperature range and are available in a space-saving, 6.5mm x 4.4mm, 20-pin, TSSOP package.

II. Manufacturing Information

A. Description/Function:	Buffered, Fast-Settling, Quad, 12-/10-/8-Bit, Voltage-Output DACs
B. Process:	C6Y
C. Number of Device Transistors:	27135
D. Fabrication Location:	Japan
E. Assembly Location:	Philippines, Thailand
F. Date of Initial Production:	January 24, 2004

III. Packaging Information

A. Package Type:	20-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0858
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	46°C/W
K. Single Layer Theta Jc:	2°C/W
L. Multi Layer Theta Ja:	37.7°C/W
M. Multi Layer Theta Jc:	2°C/W

IV. Die Information

A. Dimensions:	108 X 128 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

λ = 22.4 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the C6Y Process results in a FIT Rate of 0.90 @ 25C and 15.55 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DB12-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltage per JESD78.

Table 1

Reliability Evaluation Test Results

MAX5580AEUP+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data